

2.5V Drive Nch + Nch MOSFET

AEC-Q101 Qualified

UM6K31NFHA

Structure

Silicon N-channel MOSFET

●Features

- 1) High speed switing.
- 2) Small package(UMT6).
- 3) Low voltage drive(2.5V drive).

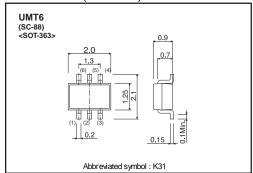
Application

Switching

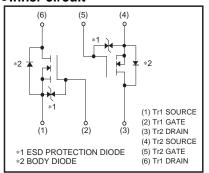
Packaging specifications

| | Package | Taping |
|----------|------------------------------|--------|
| Type | Code | TCN |
| | Basic ordering unit (pieces) | 3000 |
| UM6K31NF | 0 | |

●Dimensions (Unit : mm)



●Inner circuit



◆Absolute maximum ratings (Ta = 25°C)

| Parameter | | Limits | Unit |
|------------------------------|-------------------------------------|--|---|
| Drain-source voltage | | 60 | V |
| Gate-source voltage | | ±20 | V |
| Continuous | I_D | ±250 | mA |
| Pulsed | I _{DP} *1 | ±1 | А |
| Continuous | Is | 125 | mA |
| Pulsed | I _{sp} *1 | 1 | Α |
| Power dissipation | | 150 | mW / TOTAL |
| | | 120 | mW / ELEMENT |
| Channel temperature | | | °C |
| Range of storage temperature | | | °C |
| | Continuous Pulsed Continuous Pulsed | $\begin{array}{c c} & V_{DSS} \\ \hline & V_{GSS} \\ \hline \\ Continuous & I_D \\ \hline \\ Pulsed & I_{DP} & ^{*1} \\ \hline \\ Continuous & I_s \\ \hline \\ Pulsed & I_{sp} & ^{*1} \\ \hline \\ & P_D & ^{*2} \\ \hline \\ & Tch \\ \hline \end{array}$ | $\begin{array}{c ccccccccccccccccccccccccccccccccccc$ |

^{*1} Pw≤10µs, Duty cycle≤1%

●Thermal resistance

| Parameter | Symbol | Limits | Unit |
|--------------------|------------|--------|---------------|
| Channel to ambient | Rth (ch-a) | 833 | °C / W /TOTAL |
| Charmer to ambient | | 1042 | °C/W/ELEMENT |

^{*} Each terminal mounted on a recommended land.

^{*2} Each terminal mounted on a recommended land.

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●Electrical characteristics (Ta = 25°C)

<It is the same ratings for Tr1 and Tr2.>

| Parameter | Symbol | Min. | Тур. | Max. | Unit | Conditions |
|---------------------------------|-----------------------|------|------|------|------|--|
| Gate-source leakage | I _{GSS} | • | - | ±10 | μA | $V_{GS}=\pm20V, V_{DS}=0V$ |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | 60 | - | - | V | I _D =1mA, V _{GS} =0V |
| Zero gate voltage drain current | I _{DSS} | 1 | - | 1 | μA | V_{DS} =60V, V_{GS} =0V |
| Gate threshold voltage | V _{GS (th)} | 1.0 | - | 2.3 | V | V _{DS} =10V, I _D =1mA |
| | | 1 | 1.7 | 2.4 | Ω | I _D =250mA, V _{GS} =10V |
| Static drain-source on-state | D * | - | 2.1 | 3.0 | | I _D =250mA, V _{GS} =4.5V |
| resistance | R _{DS (on)} | - | 2.3 | 3.2 | | I _D =250mA, V _{GS} =4.0V |
| | | - | 3.0 | 12.0 | | I _D =10mA, V _{GS} =2.5V |
| Forward transfer admittance | I Y _{fs} I* | 0.25 | - | - | S | I _D =250mA, V _{DS} =10V |
| Input capacitance | C _{iss} | 1 | 15 | - | pF | V _{DS} =25V |
| Output capacitance | C _{oss} | - | 4.5 | - | pF | V _{GS} =0V |
| Reverse transfer capacitance | C _{rss} | - | 2.0 | - | pF | f=1MHz |
| Turn-on delay time | t _{d(on)} * | - | 3.5 | - | ns | I _D =100mA, V _{DD} ≒ 30V |
| Rise time | t _r * | - | 5 | - | ns | V _{GS} =10V |
| Turn-off delay time | t _{d(off)} * | - | 18 | - | ns | R _L ≒ 300Ω |
| Fall time | t _f * | - | 28 | - | ns | $R_G=10\Omega$ |

^{*}Pulsed

●Body diode characteristics (Source-Drain) (Ta = 25°C)

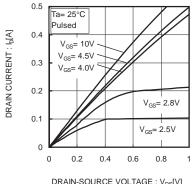
<It is the same ratings for Tr1 and Tr2.>

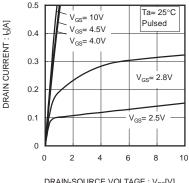
| Parameter | Symbol | Min. | Тур. | Max. | Unit | Conditions |
|-----------------|-------------------|------|------|------|------|--|
| Forward voltage | V _{SD} * | - | - | 1.2 | V | I _s =250mA, V _{GS} =0V |

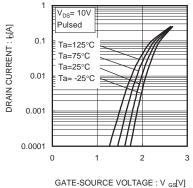
^{*}Pulsed

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•Electrical characteristic curves





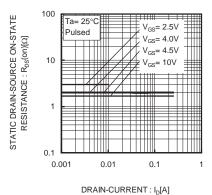


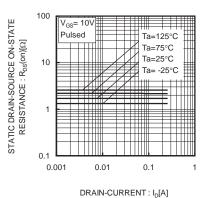
DRAIN-SOURCE VOLTAGE : V_{DS}[V]

Fig.1 Typical Output Characteristics(I)

 $\label{eq:decomposition} \begin{aligned} & \mathsf{DRAIN}\text{-}\mathsf{SOURCE}\;\mathsf{VOLTAGE}: \mathsf{V}_{\mathsf{DS}}\![\mathsf{V}] \\ & \mathsf{Fig.2}\;\mathsf{Typical}\;\mathsf{Output}\;\mathsf{Characteristics}(\mathbb{I}) \end{aligned}$

Fig.3 Typical Transfer Characteristics





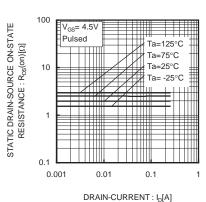
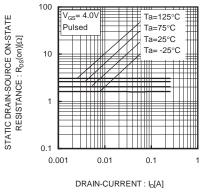


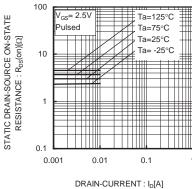
Fig.4 Static Drain-Source On-State

Resistance vs. Drain Current(I)

Fig.5 Static Drain-Source On-State Resistance vs. Drain Current(Ⅱ)

Fig.6 Static Drain-Source On-State
Resistance vs. Drain Current(Ⅲ)





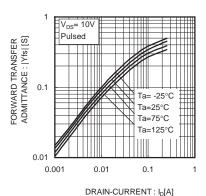
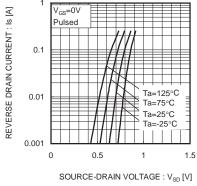


Fig.7 Static Drain-Source On-State
Resistance vs. Drain Current(IV)

Fig.8 Static Drain-Source On-State
Resistance vs. Drain Current([V])

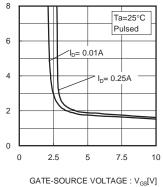
Fig.9 Forward Transfer Admittance vs. Drain Current

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8 STATIC DRAIN-SOURCE ON-STATE RESISTANCE : $R_{DS}(ON)[\Omega]$ 6 4 2 0 0



Ta=25°C $V_{DD} = 30V$ SWITCHING TIME: t [ns] V_{GS}=10V $R_G=10\Omega$ 100 10 0.01 0.1 $\mathsf{DRAIN}\text{-}\mathsf{CURRENT}:\mathsf{I}_\mathsf{D}\![\mathsf{A}]$

Fig.10 Reverse Drain Current vs. Sourse-Drain Voltage

Fig.11 Static Drain-Source On-State Resistance vs. Gate Source Voltage

Fig.12 Switching Characteristics

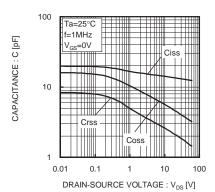


Fig.13 Typical Capacitance vs. Drain-Source Voltage

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●Measurement circuits

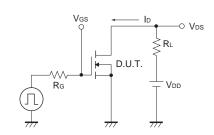


Fig.1-1 Switching time measurement circuit

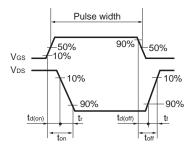


Fig.1-2 Switching waveforms

●Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

Notice

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| JAPAN | USA | EU | CHINA |
|---------|---------|------------|--------|
| CLASSⅢ | OL ACOM | CLASS II b | ОГУООШ |
| CLASSIV | CLASSⅢ | CLASSⅢ | CLASSⅢ |

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - If Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

Precaution for Product Label

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

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